

ABSTRACT OF THE DISCLOSURE

A method for fabricating a semiconductor device, which includes the process step of polishing a substrate using CMP. To suppress the generation of scars and scratches on a wafer surface, in the polishing process, a tube-type slurry supply pump **15** is used to supply 5 slurry. Then, in the tube-type slurry supply pump **15**, a vinyl chloride type tube is used as a tube **12** for supplying a slurry.